



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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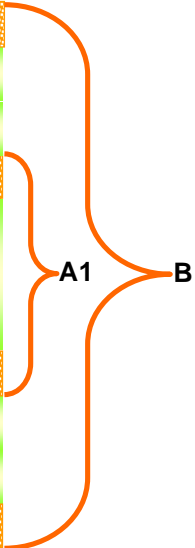






**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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04 171 FR4 35 L71.105 P18

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_171\_FR4\_35\_L71.105\_p18

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		
	180 $\mu$	Prepreg	(180 $\mu$ PrePreg-Type: 7628)	
	180 $\mu$	Prepreg		
Layer-2	105 $\mu$	Copper		
	710 $\mu$	L-FR4		
Layer-3	105 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-99	35 $\mu$	Copper	